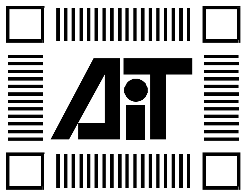

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PRIMA-BOND

ME7650-RC

Snap Curing
Solvent Free, Thixotropic Electrically Insulating Epoxy Paste Adhesive
< 20 ppm Ionic Impurities

IDEAL FOR:

Large Area Die Attach
Component Attach Including SMT
Substrate Attach
Sealing

DESCRIPTION:

ME7650-RC is a low viscosity version of ME7150 for snap curing application. It is a reworkable, unfilled, electrically insulating and thermally conductive epoxy paste adhesive. It exhibits outstanding flexibility for bonding materials with highly mismatched CTE's (i.e., alumina to aluminum, silicon to copper). The stress-free flexible characteristic of this material makes it useful for bonding high-powered, large area die and components.

ME7650-RC can be cured rapidly at 150-180ºC for approximately 60 seconds without creating voids. It can be readily reworked at 80-100ºC.

TYPICAL PROPERTIES*

Property	Value
Electrical Resistivity (150 ºC/ 90 second)	>1x10 ^{14} ohm-cm
Dielectric Strength (Volts/mil)	>750
Glass Transition Temp.(ºC)	-25 ±10%
Current Carrying Capabilities	N/A
Lap-Shear Strength	>1000 psi >6.9 N/mm²
Device Push-off Strength	>1200 psi >8.3 N/mm²
Hardness (Type)	60 (A) ±10%
Cured Density (gm/cc)	1.2 ±10%
Thermal Conductivity	1.4 Btu-in/hr-ft²-ºF ±10% 0.20 W/m-ºC ±10%
Linear Thermal Expansion Coeff. (ppm/ºC)	120 ±15%
Maximum Continuous Operation Temp. (ºC)	<150
Avg. Viscosity(5 rpm, 24ºC)	10,000 cp ±20%

* Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is intended to be used in manufacturing and in the final product.

AVAILABILITY:

ME7650-RC is available in syringes for automatic needle dispense applications or in jars.

CURE SCHEDULES:

Temperature	Time	Presure
140ºC	3 min	
160ºC	90 sec	
180ºC	30 sec	

APPLICATION PROCEDURES:

(1) Thaw for 30 minutes before opening jar.

(2) Dispense adhesive onto clean substrate.

(3) Cure according to one of the recommended schedules.

SHELF LIFE:

Storage temperature	Shelf Life
-40ºC	1 yr
0ºC	3 mo
25ºC	5 da

CAUTION: This product may cause skin irritation. Avoid skin contact. If contact does occur, wash immediately with soap and water. Please refer SDS for more details

The information contained herein is believed to be reliable. All recommendations or suggestions are made without guarantee inasmuch as conditions and methods of commercial use are beyond our control. Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is to be used in manufacturing and in the final product. Under no circumstance shall AI Technology be liable for accidental, consequential or other damages arising from the use or handling of this product.

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